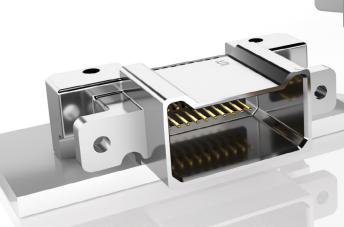


ULTRA RUGGED I/O SYSTEMS

(1.00 mm) .0394" PITCH



FEATURES & BENEFITS

- Small form factor
- Four points of contact for a reliable connection and high mating cycles
- Up to 40 positions per row
- Cable-to-cable & cable-to-board solutions
- EMI shielding limits signal degradation and optimizes performance
- Through-hole or surface mount
- 28 & 30 AWG cable



Shown actual size at 20 total positions

Hyperboloid-type contact for extreme high mating cycles



Extreme density with up to 1,450 total I/Os in a 1RU panel (29 cables at 50 total I/Os each)

KEY SPECIFICATIONS (P1PD(X), B1SD(X) & P1M)

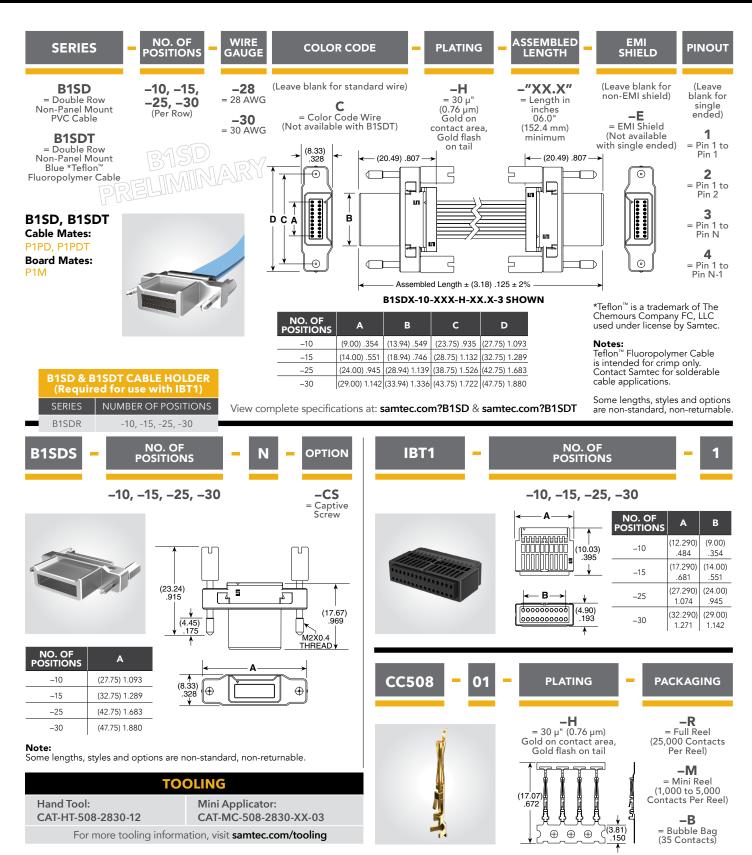
PITCH	INSULATOR MATERIAL	CONTACT MATERIAL	SHIELD MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING
1.00 mm	Liquid Crystal Polymer	Beryllium Copper	Zinc Alloy	Au over 50 μ" (1.27 μm) Ni	-10 °C to +80 °C (PVC) -40 °C to +125 °C (*Teflon™ Fluoropolymer)	3.8 A per pin (2 pins powered)	200 VAC/ 282 VDC

^{*}Teflon™ is a trademark of The Chemours Company FC, LLC used under license by Samtec.





(1.00 mm) .0394" PITCH • NON-PANEL MOUNT I/O CABLE/COMPONENTS



View complete specifications at: samtec.com?B1SDS, samtec.com?IBT1 & samtec.com?CC508